

HEAT AND MASS TRANSFER IN A  
VERTICAL EPITAXIAL REACTOR.

2. NONSYMMETRICAL HEATING OF THE REACTOR

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A numerical investigation yields the distribution of dimensionless deposition rate along an epitaxial reactor in the form of a vertical plane channel with heated and cooled walls.

The first part of this study [1] described heat and mass transfer in an epitaxial reactor in the form of a symmetrically heated vertical channel. In another type of reactor which is widely used, the walls are cooled and their temperature is considerably below the temperature of the deposition surface. These differences account for the differences in heat and mass transfer in the given reactor and the reactor described in [1].

Reactors with "cold" walls are usually made in the form of a cooled vertical segment of a tube (quartz or metal) enclosing a coaxially-positioned substrate holder in the form of a polyhedral pyramid [2]. In commercial reactors, the width of the annular gap between the reactor wall and the substrate holder is much smaller than the diameter of the reactor. For purposes of simplification, this allows us to represent the gap as a plane channel. It is shown schematically in Fig. 1.

The thin plate-substrates 1 are located on the flat substrate holder 2 and heated to the deposition temperature. The wall of the reactor 3 is cooled to a temperature considerably below the deposition temperature. The gas mixture is fed downward into the reactor as shown by the arrow.

In the boundary-layer approximation, the equations describing heat and mass transfer in the given reactor are the same as Eqs. (2-5) in [1]. The boundary conditions have the form:

$$\begin{aligned} \tilde{x} = 0, \quad 0 < \tilde{y} < 1, \quad \tilde{u} = 1, \quad \tilde{T} = 1, \quad c_1 = c_{01}; \quad \tilde{x} \geq 0, \quad y = y_s, \quad \tilde{u} = 0, \\ \tilde{v} = \tilde{v}_s, \quad \tilde{T} = \tilde{T}_s, \quad c_1 = 0; \quad \tilde{x} \geq 0, \quad \tilde{y} = 1, \quad \tilde{u} = \tilde{v} = 0, \quad \tilde{T} = \tilde{T}_w, \end{aligned} \quad (1)$$

$$\frac{\partial c_1}{\partial \tilde{y}} + \frac{\alpha_T c_1 (1 - c_1)}{\tilde{T}_w} \frac{\partial \tilde{T}}{\partial \tilde{y}} = 0.$$

The geometric characteristics of the reactor and the space coordinates ( $h, \alpha, x, y, y_s$ ) are shown in Fig. 1, while the remaining notation coincides with that used in [1].

At  $\alpha = 0^\circ$ , the deposition angle decreases with increasing distance from the reactor inlet (see Fig. 2) due to depletion of silane from the gas mixture. However, this relation is monotonic. As in a symmetrically heated channel [1], the presence of a maximum or an inflection point on the curve  $Nu_{0D}(\tilde{x}_T)$  is connected with a reduction in the contribution of free convection and thermodiffusion.

The effect of these factors - which is to decrease deposition rate - diminishes toward the end of the initial thermal section. The role of free convection increases with a decrease in wall temperature. The effect of free convection is smaller in a convergent channel and disappears at a smaller value of  $\tilde{x}_T$  than in a parallel channel (Fig. 2).

As is shown in Fig. 2, free convection reduces silicon deposition rate to the greatest extent in the region of small  $\tilde{x}_T$ . Meanwhile, the value of the ratio of the numbers  $Nu_{0D}$

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TABLE 1. Critical Values of the Complex Ga/Re for Different Conditions of Silicon Epitaxy

Num-ber of regime	$T_s$	$T_w$	$T_0$	$u_0$ , m/sec	$h_0$ , m	$\alpha$ , deg	Ga/Re
	K						
1	13 23	573	293	0,22	0,03	0	391
2	13 23	573	573	0,20	0,05	0	199
3	13 23	573	293	0,21	0,03	3	410
4	13 23	573	293	0,18	0,03	5	478
5	14 23	323	293	0,45	0,05	0	531
6	14 23	323	293	0,35	0,05	2	683

determined with and without allowance for free convection depends only slightly on  $\bar{x}_T$  in the range  $0.005 \leq \bar{x}_T \leq 0.03$ .

As in the symmetrically heated channel, the effect of free convection on  $Nu_{0D}$  is characterized by the ratio Ga/Re. At constant  $T_s$ ,  $T_0$ , and  $T_w$ , the values of  $Nu_{0D}$  obtained with different Ga/Re are generalized by a single straight line (Fig. 3). A change in  $T_0$  and  $T_w$  is accompanied by a change in  $Nu_{0D}$  and the slope of the curves  $Nu_{0D}$  (Ga/Re). At  $T_s = 1323$  and  $T_w = 573$  K, an increase in  $T_0$  from 293 to 573 K leads to a reduction in  $Nu_{0D}$  and an increase in the dependence of this quantity on Ga/Re. In contrast to  $Nu_{0D}$ , the dimensional rate of deposition increases with an increase in  $T_0$ .

The increase in the dependence of  $Nu_{0D}$  on free convection (the increase in the slope of the curve  $Nu_{0D}$  (Ga/Re)) is evidently connected with weakening of the effect of thermodiffusion.

A reduction in reactor temperature leads to a reduction in  $Nu_{0D}$  (Fig. 3), which can be attributed to the role of free convection and thermodiffusion.

At high values of Ga/Re, a reverse flow develops along the deposition surface. With a decrease in Ga/Re, the separation point moves from the inlet farther into the channel. The distance to this point cannot exceed the length of the zone in which free convection plays an important role, i.e.  $\bar{x}_T = 0.1-0.15$  (see Fig. 2). Thus, at Ga/Re lower than a certain critical value  $(Ga/Re)_{cr}$ , recirculation does not occur for any value of  $\bar{x}_T$ .

The value of  $(Ga/Re)_{cr}$  is given in Table 1 for certain combinations of conditions typical of the deposition of silicon from a mixture of  $SiH_4$  and  $H_2$ . It follows from this data that the critical values of Ga/Re are lower in a reactor with "cold" walls than in a symmetrically heated reactor with "hot" walls [1]. Meanwhile,  $(Ga/Re)_{cr}$  increases with a decrease in  $T_0$ ,  $T_s$ , and  $T_w$  and an increase in the angle  $\alpha$ . It does not follow from this that the flow becomes more stable in the reactor with a decrease in gas temperature at its inlet. Conversely, an increase in  $T_0$  leads to a decrease in Ga/Re and stabilizes the flow.

Since  $Ga/Re \sim P^2$ , this criterion is small at reduced pressures in the reactor and the laminar flow is stable.

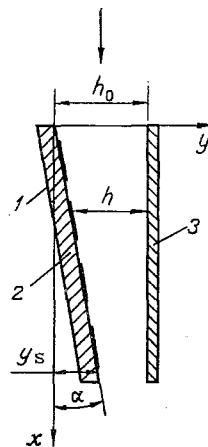


Fig. 1. Scheme of the reactor.

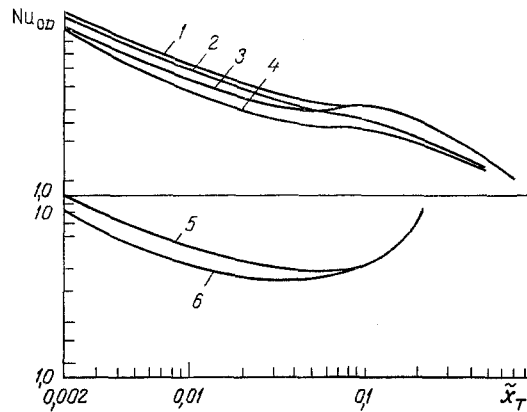


Fig. 2. Dependence of  $Nu_0D$  on  $\tilde{x}_T$  ( $P = 101$  kPa,  $X_{01} = 0.002$ ,  $T_0 = 293$  K,  $T_S = 1323$  K,  $Re = 117.1$ ):  $T_W = 323$  (2, 4, 5, 6) and  $573$  K (1, 3);  $\alpha = 0$  (1-4) and  $3^\circ$  (5, 6);  $Ga = 0$  (1, 2, 5) and  $25,180$  (3, 4, 6).

At small values of the criterion  $Ga/Re$ , free convection can be ignored. As can be determined from Fig. 3, free convection reduces  $Nu_0D$  by no more than 5% if  $Ga/Re$  does not exceed a certain value. This value is found within the range 35-65 and depends on  $T_0$  and  $T_W$ . Such values are several times lower than in the case of a symmetrically heated channel [1]. However, the low values of  $Ga/Re$  can be realized in practice with small values of  $h_0$ , heating of the gas mixture at the reactor inlet, or a reduction in pressure. For example, with  $P = 101$  kPa,  $h_0 = 0.02$  m,  $T_0 = 573$  K, and  $T_S = 1373$  K, the criterion  $Ga/Re \leq 35$  if  $u_0 \geq 0.182$  m/sec.

At reduced pressures, the criterion  $Ga/Re$  is also small when the reactor is small and the value of  $T_0$  is low. For example, at  $P = 1$  kPa,  $h_0 = 0.05$  m,  $T_0 = 293$  K, and  $u_0 = 0.2$  m/sec (under normal conditions),  $Ga/Re = 12$ .

Figure 4 shows data obtained without allowance for free convection. In a nonsymmetrically heated channel, the effect of thermodiffusion is not limited to the initial section (as it is in a symmetrically heated channel [1]) but instead extends over the entire length of the reactor (Fig. 4, a, b). However, its character depends on the relationship between the temperatures  $T_S$ ,  $T_W$ , and  $T_0$ . If  $T_0 \approx T_W$ , then the curves  $Nu_0D = f(\tilde{x}_T)$  obtained with and without allowance for thermodiffusion are approximately parallel. At  $T_W > T_0$ , thermodiffusion has a greater effect on the initial thermal section, so that the curves approach one another beyond this section (curves 5 and 7 in Fig. 4b). The result is stratification of the curves in Fig. 4c and curves 12-15 in Fig. 4d. Meanwhile, the curve is higher, the greater the temperature of the reactor wall.

The effect of thermodiffusion on deposition rate can be evaluated approximately in the same manner as in [1], i.e.

$$j/j' = 1 + K_{TD}, \quad (2)$$

where

$$K_{TD} = \left( \frac{\alpha_T X_1 (1 - X_1)}{T} \frac{\partial T}{\partial y} \right) \bigg/ \frac{\partial X_1}{\partial y}. \quad (3)$$

After simplifications, we obtained the following expression [1] from (3)

$$K_{TD} = \frac{\alpha_T (1 - \tilde{T}_S) Pr}{(1 + \tilde{T}_S) Pr_D}. \quad (4)$$

Equation (4) can be used at small  $\tilde{x}_T$ , when wall temperature does not have an effect. It can be seen from Fig. 4 that these values are approximately  $\tilde{x}_T \leq 0.03$ . For these values of  $\tilde{x}_T$ , the difference between the results calculated from Eqs. (2) and (4) and the results of numerical solutions is no greater than 2.5%.

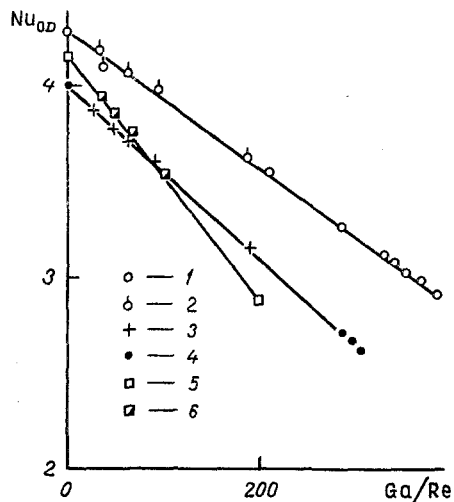


Fig. 3

Fig. 3. Effect of free convection on  $Nu_{0D}$  ( $P = 101$  kPa,  $X_{01} = 0.002$ ,  $T_S = 1323$  K):  $T_0 = 293$  (1-4) and  $573$  K (5, 6);  $T_W = 323$  (3, 4) and  $573$  K (1, 2, 5, 6);  $h_0 = 0.02$  (2, 3),  $0.03$  (1, 4, 5) and  $0.05$  m (6).

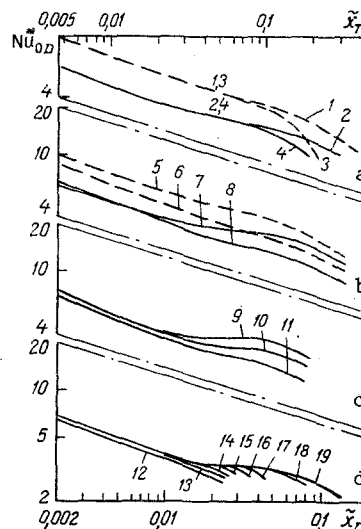


Fig. 4

Fig. 4. Change in  $Nu_{0D}$  with  $\tilde{x}_{D,T}$  in relation to different factors ( $P = 101$  kPa,  $X_{01} = 0.002$ ,  $Ga = 0$ ):  $T_0 = 293$  (1-5, 7, 9-19) and  $573$  K (6, 8);  $T_S = 1323$  (1-8, 12-19) and  $1423$  K (9-11);  $T_W = 293$  (11, 12),  $323$  (1-4),  $393$  (13),  $493$  (14),  $573$  (5-8, 10, 15-19) and  $773$  K (9);  $\alpha = 0$  (1, 2, 5-11, 19),  $2$  (18),  $3$  (3, 4) and  $5^\circ$  (12-17);  $Re \tan \alpha = 2.04$  (18),  $5.11$  (3, 4),  $12.9$  (17),  $17.2$  (16) and  $21.5$  (12-15); the dashed lines show the results obtained without thermodiffusion.

At large  $\tilde{x}_T$  and  $\tilde{x}_D$ , when we can assume that

$$\frac{\partial T}{\partial y} = \frac{T_w - T_s}{h}, \quad \frac{\partial X_1}{\partial y} = \frac{X_{01}}{h}, \quad T = \frac{T_s + T_w}{2},$$

and we can use the simplifications employed in [1], we find from Eq. (3) that

$$K_{TD} = \frac{\alpha_T (\tilde{T}_w - \tilde{T}_s)}{\tilde{T}_w + \tilde{T}_s}. \quad (5)$$

At  $T_w < T_s$ , an increase in  $T_w$  is accompanied by a decrease in the absolute value of  $K_{TD}$ . This explains the above-mentioned change in the effect of thermodiffusion along the channel.

Figure 4d shows the effect of the angle of convergence of the channel  $\alpha$ . The number  $Nu_{0D}$  was determined not from  $h_0$  but from the running value  $h = h_0 - x \tan \alpha$ . At small values of  $\alpha Re$ , the curve  $Nu_{0D}(\tilde{x}_D)$  coincides with this curve when  $\alpha = 0^\circ$  if  $\tilde{x}_D$  does not exceed a certain value of  $\tilde{x}_D$  which decreases with an increase in  $\alpha Re$ . A further increase in  $\tilde{x}_D$  leads to a decrease in  $Nu_{0D}$  compared to  $Nu_{0D}$  at  $\alpha = 0^\circ$ .

The decrease in  $Nu_{0D}$  with an increase in  $\alpha Re$  at small  $\tilde{x}_D$  is due to the decrease in the quantity  $h$ , which goes into  $Nu_{0D}$ . The dimensional mass flux  $j_1$  and, thus, the rate of deposition of the epitaxial layer decrease with an increase in  $\alpha Re$  as does the value of  $Nu'_{0D}$  calculated from  $h_0$  (see Fig. 2).

It makes sense to use  $h$  instead of  $h_0$  when determining the diffusional Nusselt number because  $Nu_{0D}$  is independent of  $\alpha Re$  within a larger range of  $\tilde{x}_D$  than is  $Nu'_{0D}$ .

As in [1], in the absence of thermodiffusion and free convection, the dependence of  $Nu_{0D}$  on  $\tilde{x}_D$  can be approximated by the formulas

$$Nu_{0D} = A \tilde{x}^{-n} \quad (6)$$

at  $\tilde{x}_D \leq 0.1$  and

$$\text{Nu}_{0D} = B \exp(-m\tilde{x}_D) \quad (7)$$

at  $\tilde{x}_D \geq 0.1$ .

In contrast to the case of a symmetrically heated channel, the quantities A, B, m, and n depend on two temperature factors:  $\psi_s = T_s/T_0$  and  $\psi_w = T_w/T_0$ . However, since the temperature factor  $\psi_w$  is usually small in reactors with cooled walls, its effect can be ignored. In fact, at  $T_0 = 293$  K, a change in  $T_w$  from 323 to 573 K causes  $\text{Nu}_{0D}$  to change by 4-6% (curves 1 and 5 in Fig. 4).

We therefore determine these quantities as a function only of  $\psi_s$ :

$$A = 0.66 \exp(0.17\psi_s), \quad n = 0.39 \exp(-0.053\psi_s), \quad B = 1.3 \cdot 0.1^{-12} A, \quad (8)$$
$$m = 0.45\psi_s + 1.46.$$

In the range  $1 \leq \psi_s \leq 4.5$  the results of the numerical solution and results calculated from approximate formulas (6-8) differ by no more than 5% throughout the range  $0.002 \leq \tilde{x}_D \leq 0.2$  except for the neighborhood of the point  $\tilde{x}_D \approx 0.1$ . Here, this difference increases to about 8%.

The effect of thermodiffusion and free convection can be evaluated from the relations shown in Figs. 2-4 and from Eqs. (2-5).

A similar calculation of heat fluxes in a reactor was performed in [4], while temperature and concentration profiles described by polynomials were presented in [3, 4].

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#### EFFECT OF THE FORM OF THE TEMPERATURE DEPENDENCE OF SURFACE TENSION ON MOTION AND HEAT TRANSFER IN A LAYER OF LIQUID DURING LOCAL HEATING

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The nonsteady distribution of velocity and temperature in a layer of liquid during thermoconvective motion caused by local heating is calculated. The cases of an increasing and decreasing temperature dependence of surface tension are examined.

A large number of studies has been devoted to explaining the relative role of thermocapillary (TC) and thermogravitational (TG) convection in the motion of a liquid in a system with temperature gradients. These studies have become particularly important in connection with investigation of the behavior of liquids under conditions of reduced gravitation [1, 2].

Until recently, it was usually assumed when theoretically describing thermocapillary motion that surface tension decreased linearly with an increase in temperature (positive

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